

Bill of materials

Item	Part	Quantity	Value	Part name	Manufacturer	Description	Package Name	Standard Dimensions mm (inch)
1	IC1	1	-	TPD4162F	TOSHIBA	IPD	HSSOP31	11.93 x 17.5
2	Q1	1	-	SSM3K56MFV	TOSHIBA	MOSFET	VESM	1.2 x 1.2
3	S1,S2,S3	3		HW-101A	AKM	Hall element	4SOP	2.9 x 2.9
4	R1	1	1.2 Ω	ERJ1TRQF1R2U	Panasonic	1 W ±1 %		6.4 x 3.2 (2412)
5	R2	1	27 kΩ			100 mW ±1 %		1.6 x 0.8 (0603)
6	R3	1	5.1 kΩ			100 mW ±5 %		1.6 x 0.8 (0603)
7	R4,R8	1	100 Ω			100 mW ±5 %		1.6 x 0.8 (0603)
8	R5,R6	2	82 Ω			100 mW ±5 %		1.6 x 0.8 (0603)
9	R9	1	2 MΩ			250 mW ±1 %		2.0 x 1.2 (0805)
10	C1,C2,C3	3	2.2 μF			Ceramic, 25 V, ±10 %		2.0 x 1.2 (0805)
11	C4,C14	2	1 nF			Ceramic, 25 V, ±5 %		1.6 x 0.8 (0603)
12	C5	1	10 μF			Ceramic, 25 V, ±10 %		2.0 x 1.2 (0805)
13	C6,C15	2	100 nF			Ceramic, 25 V, ±10 %		1.6 x 0.8 (0603)
14	C12,C13, C19	3	220 nF			Ceramic, 630 V, ±10 %		4.5 x 3.2 (1812)
15	C16,C17, C18	3	1 nF			Ceramic, 50 V, ±10 %		1.6 x 0.8 (0603)
16	C20	1	470 pF			Ceramic, 50 V, ±5%		1.6 x 0.8 (0603)
17	C21	1	1 μF			Ceramic, 25 V, ±10%		2.0 x 1.2 (0805)

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